L Number	Hits	Search Text	DB	Time stamp
1	106	interconnect$4 and ((first adj (etch$4 or clean$4 or treat$4 or anneal$4)) same (copper or Cu)) and ((second adj (etch$4 or clean$4 or treat$4 or anneal$4)) same (copper or Cu)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 13:06
2	748421	interconnect$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 13:06
3	40	interconnect$4 and ((first adj (etch$4 or clean$4 or treat$4 or anneal$4)) with (copper or Cu)) and ((second adj (etch$4 or clean$4 or treat$4 or anneal$4)) with (copper or Cu)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 13:41
4	6	interconnect$4 and ((first adj (anneal$4 or treat$4)) with (copper or Cu)) and ((second adj (treat$4 or anneal$4)) with (copper or Cu)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/08 13:43